

SID

Factory: Rot am See

Article:

ML6

Provided:

Customer:

Date:

03.04.2026

WÜRTH  
ELEKTRONIK  
MORE THAN  
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	 B00
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	152		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		
		105	L2	
C-RS-FR4-ML-0.203mm-105+105-TG150-HF-...	50203085	203		
		105	L3	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	257		
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		
		105	L4	
C-RS-FR4-ML-0.203mm-105+105-TG150-HF-...	50203085	203		
		105	L5	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	152		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	

Thickness after Pressing

B00:

1440 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1595 µm

Dmin:

1285 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1550 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1705 µm

Dmin:

1395 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

1457 µm

Version 1.2.20.35

© Würth Elektronik